Description

The PCB-TSSOP8 adapter module is designed to convert integrated circuits (IC) in 8-pin TSSOP or MSOP packages to a top mounted DIP module. PCB-TSSOP8 module is a pin compatible drop in replacement for DIP devices. This adapter was designed for engineers, students and hobbyists who are looking for a quick way of connect surface mount components to the breadboard.

Features

- SMD/SMT TSSOP or MSOP packages with 0.65mm pitch (double sided)
- TSSOP8 SMD body width 3.0mm (0.118 inches) / SOT505-2
- MSOP8 SMD body width 2.8mm (0.110 inches) / MO-187-DA JEDEC
- Double rows standard 2.54mm pitch DIP header pins (7.62mm/300mil)
- Header pins drill 0.8mm
- Small and compact in size 10x10mm
- Board thickness 1.5mm
- White marking print on both sides
- High quality FR4 material
- Copper final thickness 35µm
- Green solder-stop on both sides
- HAL lead-free surface
- Electrical test

Package Information

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Ordering Information

Ordering code / Item-No.: PCB-TSSOP8